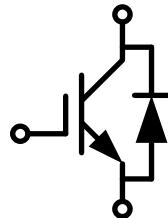


## IGBT Discrete with Anti-Parallel Diode

### 电气特性/ Features and Benefits:

- 700V 沟槽栅/场终止工艺  
700V trench gate/field termination process
- 低开关损耗  
Low switching losses
- V<sub>CESAT</sub> 正温度系数  
V<sub>CESAT</sub> has a positive temperature coefficient



### 典型应用/ Applications:

- 充电桩  
Charging station
- 不间断电源  
Uninterruptible power supplies
- 逆变器  
Inverters



V<sub>CES</sub> = 700V, I<sub>C nom</sub> = 60A / I<sub>CRM</sub> = 180A

### 关键性能和程序参数 / Key Performance and Package Parameters

Type	V <sub>CE</sub>	I <sub>C</sub>	V <sub>CESAT</sub> , T <sub>vj</sub> =25°C	T <sub>vjmax</sub>	Package
SD60R07A6U	700V	60A	1.47V	175°C	TO-247-3L

## 双极晶体管/IGBT

### 最大额定值 / Maximum Ratings

Parameter	Conditions	Symbol	Value	Unit
集电极-发射极电压 Collector-Emitter voltage	T <sub>vj</sub> =25°C	V <sub>CES</sub>	700	V
连续集电极直流电流 Continuous DC collector current	T <sub>C</sub> =100°C, T <sub>vj max</sub> =175°C	I <sub>C nom</sub>	60	A
集电极重复峰值电流 Repetitive peak collector current	t <sub>p</sub> =1 ms	I <sub>CRM</sub>	180	A
栅极-发射极电压 Gate emitter voltage		V <sub>GE</sub>	±20	V
瞬变栅极-发射极电压 Transient Gate-emitter voltage	t <sub>p</sub> ≤ 10μs, D<0.010	V <sub>GE</sub>	±25	V

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总功率损耗 Power dissipation	T <sub>c</sub> =25°C T <sub>c</sub> =100°C	P <sub>tot</sub>	440 220	W
在开关状态下温度 Temperature under switching conditions		T <sub>vj op</sub>	-40...+175	°C
储存温度 Storage temperature		T <sub>stg</sub>	-40...+150	°C

## 热特性 / Thermal Characteristics

Parameter	Conditions	Symbol	Value			Unit
			Min.	Typ.	Max.	
IGBT 热阻, 结-壳 IGBT thermal resistance, junction - case		R <sub>th(j-C)</sub>		0.34		K/W
二极管热阻, 结-壳 Diode thermal resistance, junction - case		R <sub>th(j-C)</sub>		0.49		K/W

## 特征值 / Characteristic Values

Parameter	Conditions	Symbol	Value			Unit
			Min.	Typ.	Max.	
集电极-发射极饱和电压 Collector-Emitter saturation voltage	V <sub>GE</sub> =15V, I <sub>c</sub> =60A V <sub>GE</sub> =15V, I <sub>c</sub> =60A V <sub>GE</sub> =15V, I <sub>c</sub> =60A	T <sub>vj</sub> =25°C T <sub>vj</sub> =150°C T <sub>vj</sub> =175°C	V <sub>CEsat</sub>	1.47 1.81 1.86	1.90	V
栅极-发射极阈值电压 Gate-Emitter threshold voltage	I <sub>c</sub> =0.6mA, V <sub>GE</sub> = V <sub>CE</sub>	T <sub>vj</sub> =25°C	V <sub>GE(th)</sub>	4.4	5.0	5.6
跨导 Transconductance	V <sub>CE</sub> =20V, I <sub>c</sub> =60A	G <sub>fs</sub>		96		S
输入电容 Input capacitance	f=100kHz, V <sub>CE</sub> =25 V, V <sub>GE</sub> =0 V	C <sub>ies</sub>		8039		pF
输出电容 Output capacitance		C <sub>oes</sub>		239		pF
反向传输电容 Reverse transfer capacitance		C <sub>res</sub>		136		pF
门极电荷 Gate charge	I <sub>c</sub> = 60A, V <sub>GE</sub> = 15 V, V <sub>CE</sub> = 560V	T <sub>vj</sub> =25°C	Q <sub>G</sub>		742	nC
集电极-发射极截止电流 Collector-emitter cut-off current	V <sub>CE</sub> =700V, V <sub>GE</sub> = 0 V	T <sub>vj</sub> =25°C	I <sub>CES</sub>		1	mA
栅极-发射极漏电流 Gate-emitter leakage current	V <sub>CE</sub> =0 V, V <sub>GE</sub> = 20 V	T <sub>vj</sub> =25°C	I <sub>GES</sub>		200	nA
开通延迟时间 Turn-on delay time	I <sub>c</sub> =60A, V <sub>CE</sub> =400V V <sub>GE</sub> =±15 V, R <sub>G</sub> =8Ω (电感负载) / (inductive load)	T <sub>vj</sub> =25°C T <sub>vj</sub> =175°C	t <sub>d(on)</sub>	36 30		ns
上升时间 Rise time	I <sub>c</sub> =60A, V <sub>CE</sub> =400V V <sub>GE</sub> =±15 V, R <sub>G</sub> =8Ω (电感负载) / (inductive load)	T <sub>vj</sub> =25°C T <sub>vj</sub> =175°C	t <sub>r</sub>	112 97		ns

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关断延迟时间 Turn-off delay time	I <sub>C</sub> =60A, V <sub>CE</sub> =400V V <sub>GE</sub> =±15 V, R <sub>G</sub> =8Ω (电感负载) / (inductive load)	T <sub>vj</sub> =25°C T <sub>vj</sub> =175°C	t <sub>d(off)</sub>		182 212		ns
下降时间 Fall time	I <sub>C</sub> =60A, V <sub>CE</sub> =400V V <sub>GE</sub> =±15 V, R <sub>G</sub> =8Ω (电感负载) / (inductive load)	T <sub>vj</sub> =25°C T <sub>vj</sub> =175°C	t <sub>r</sub>		49 78		ns
开通损耗能量 (每脉冲) Turn-on energy loss per pulse	I <sub>C</sub> =60A, V <sub>CE</sub> =400V V <sub>GE</sub> =±15 V, R <sub>G</sub> =8Ω di/dt=600A/us(T <sub>vj</sub> =175°C) (电感负载) / (inductive load)	T <sub>vj</sub> =25°C T <sub>vj</sub> =175°C	E <sub>on</sub>		2.76 3.53		mJ
关断损耗能量 (每脉冲) Turn-off energy loss per pulse	I <sub>C</sub> =60A, V <sub>CE</sub> =400V V <sub>GE</sub> =±15 V, R <sub>G</sub> =8Ω dv/dt=10000V/us(T <sub>vj</sub> =175°C) (电感负载) / (inductive load)	T <sub>vj</sub> =25°C T <sub>vj</sub> =175°C	E <sub>off</sub>		0.75 1.13		mJ

## 二极管/Diode

### 最大额定值 / Maximum Ratings

Parameter	Conditions	Symbol	Value	Unit
反向重复峰值电压 Repetitive peak reverse voltage	T <sub>vj</sub> =25°C	V <sub>RRM</sub>	700	V
连续正向直流电流 Continuous DC forward current	T <sub>C</sub> =100°C, T <sub>vj max</sub> =175°C	I <sub>F</sub>	60	A
正向重复峰值电流 Repetitive peak forward current	t <sub>p</sub> =1ms	I <sub>FRM</sub>	180	A

### 特征值 / Characteristic Values

Parameter	Conditions	Symbol	Value			Unit
			Min.	Typ.	Max.	
正向电压 Forward voltage	I <sub>F</sub> =60A, V <sub>GE</sub> =0V	V <sub>F</sub>		1.45	2.00	V
	I <sub>F</sub> =60A, V <sub>GE</sub> =0V			1.55		
	I <sub>F</sub> =60A, V <sub>GE</sub> =0V			1.52		
反向恢复峰值电流 Peak reverse recovery current	I <sub>F</sub> =60A, -di <sub>F</sub> /dt=600A/μs(T <sub>vj</sub> =175°C)	I <sub>RM</sub>		18		A
	V <sub>R</sub> =400V, V <sub>GE</sub> =-15V			30		
	T <sub>vj</sub> =25°C T <sub>vj</sub> =175°C					
反向恢复电荷 Reverse Recovered charge	I <sub>F</sub> =60A, -di <sub>F</sub> /dt=600A/μs(T <sub>vj</sub> =175°C)	Q <sub>rr</sub>		1.55		μC
	V <sub>R</sub> =400V, V <sub>GE</sub> =-15V			3.99		
	T <sub>vj</sub> =25°C T <sub>vj</sub> =175°C					
反向恢复时间 Reverse Recovery Time	I <sub>F</sub> =60A, -di <sub>F</sub> /dt=600A/μs(T <sub>vj</sub> =175°C)	t <sub>rr</sub>		142		ns
	V <sub>R</sub> =400V, V <sub>GE</sub> =-15V			210		
	T <sub>vj</sub> =25°C T <sub>vj</sub> =175°C					
反向恢复损耗 (每脉冲) Reverse recovered energy	I <sub>F</sub> =60A, -di <sub>F</sub> /dt=600A/μs(T <sub>vj</sub> =175°C)	E <sub>rec</sub>		0.38		mJ
	V <sub>R</sub> =400V, V <sub>GE</sub> =-15V			0.97		
	T <sub>vj</sub> =25°C T <sub>vj</sub> =175°C					

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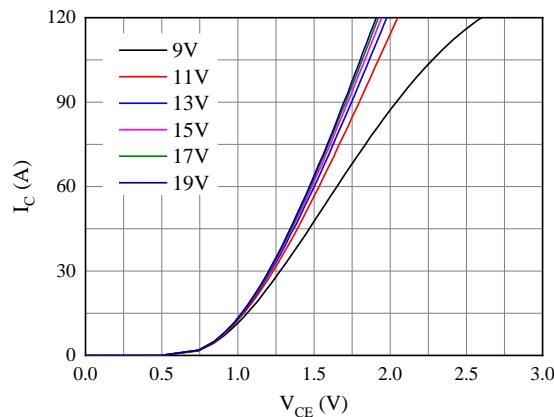
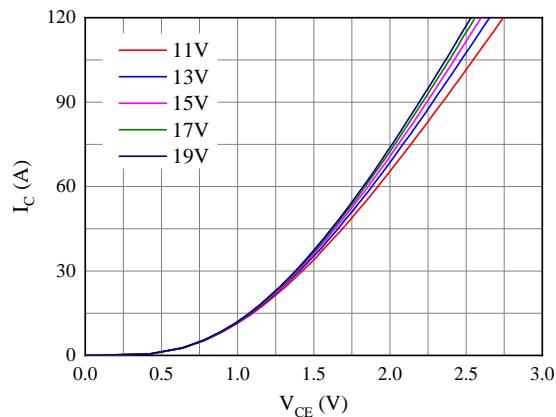
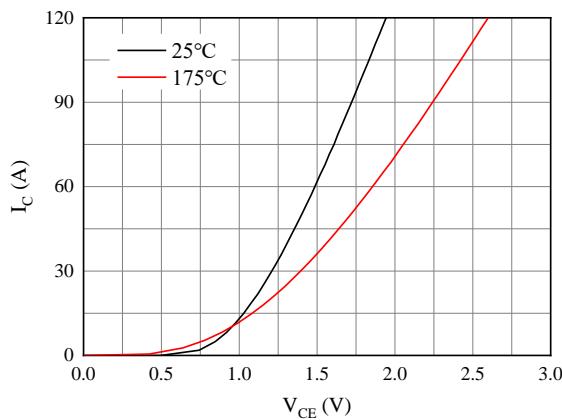
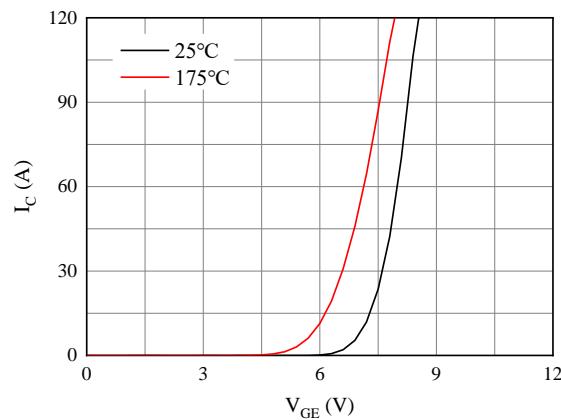
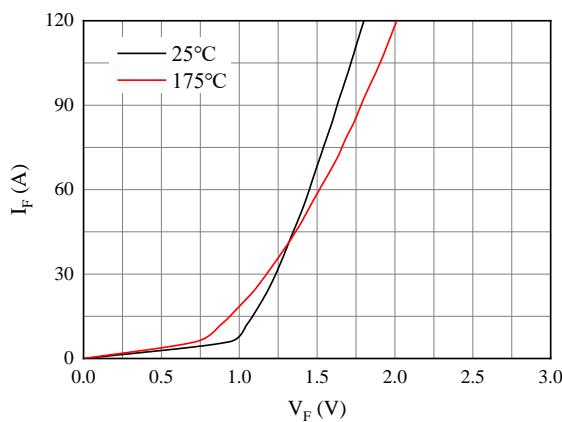
图 1. 典型输出特性 ( $T_{vj}=25^{\circ}\text{C}$ )Figure 1. Typical output characteristics ( $T_{vj}=25^{\circ}\text{C}$ )图 2. 典型输出特性 ( $T_{vj}=175^{\circ}\text{C}$ )Figure 2. Typical output characteristics ( $T_{vj}=175^{\circ}\text{C}$ )图 3. 典型输出特性 ( $V_{GE}=15\text{V}$ )Figure 3. Typical output characteristics ( $V_{GE}=15\text{V}$ )图 4. 典型传输特性( $V_{CE}=20\text{V}$ )Figure 4. Typical transfer characteristic( $V_{CE}=20\text{V}$ )

图 5. 正向偏压特性 二极管

Figure 5. Forward characteristic of Diode

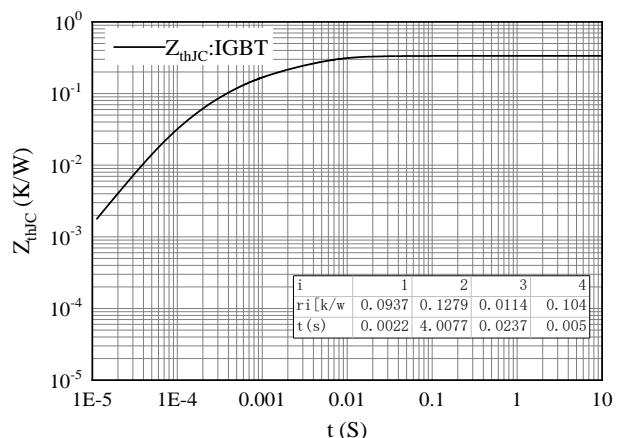


图 6. 瞬态热阻抗 IGBT

Figure 6. Transient thermal impedance IGBT,  
 $Z_{thJC}=f(t)$

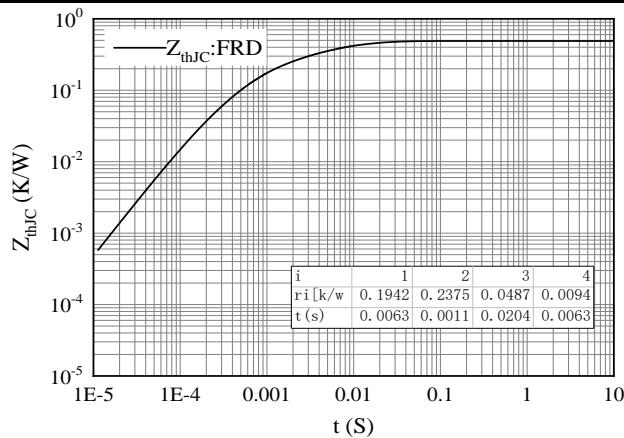


图 7. 瞬态热阻抗 IGBT  
Figure 7. Transient thermal impedance IGBT,  
 $Z_{thJC}=f(t)$

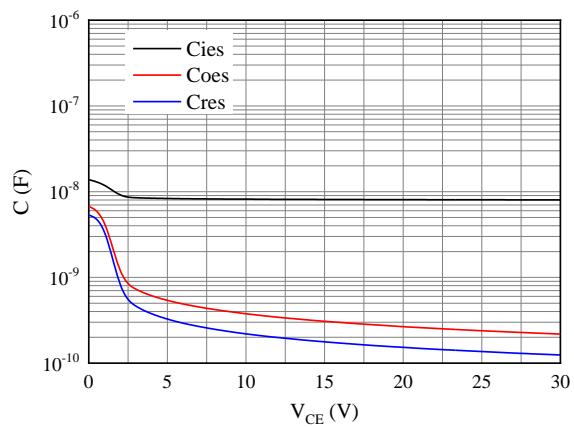


图 8. 电容特性  
Figure 8. Capacitance characteristic

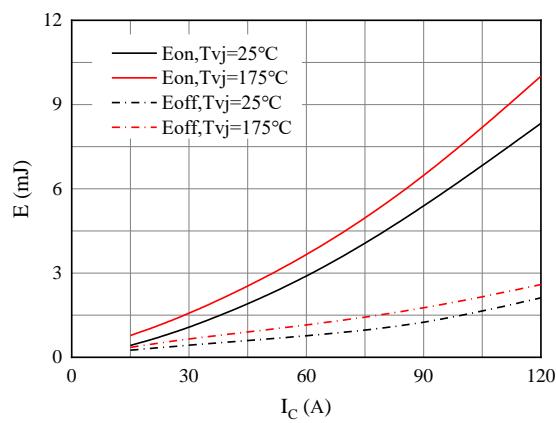


图 9. 开关损耗  
Figure 9. Switching losses of IGBT  
 $V_{GE}=\pm 15\text{V}$ ,  $R_{gon}=8\Omega$ ,  $R_{goff}=8\Omega$ ,  $V_{CE}=400\text{V}$

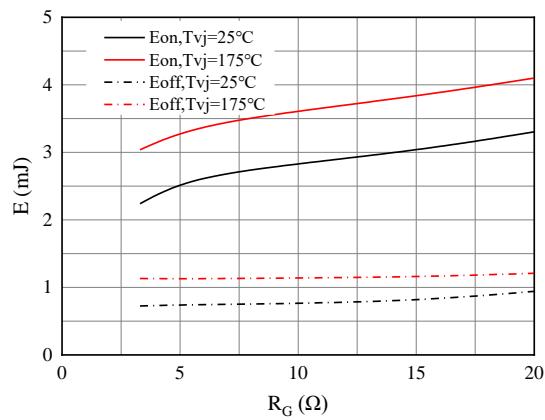


图 10. 开关损耗  
Figure 10. Switching losses of IGBT  
 $V_{GE}=\pm 15\text{V}$ ,  $I_C=60\text{A}$ ,  $V_{CE}=400\text{V}$

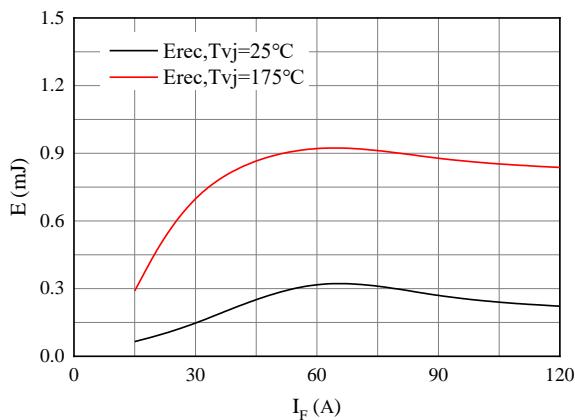


图 11. 开关损耗 二极管  
Figure 11. Switching losses of Diode  
 $R_{gon}=8\Omega$ ,  $V_{CE}=400\text{V}$

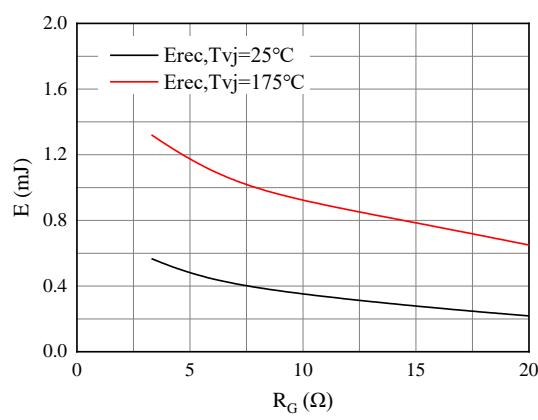
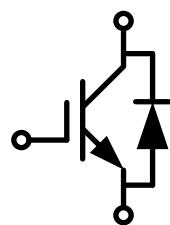


图 12. 开关损耗 二极管  
Figure 12. Switching losses of Diode  
 $I_F=60\text{A}$ ,  $V_{CE}=400\text{V}$

## 接线图 / Circuit diagram



## 封装尺寸 / Package outlines

